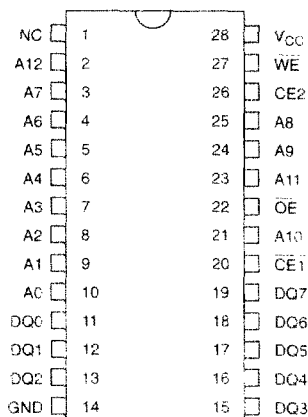


FEATURES

- Low power CMOS design
- Standby current
 - 50 nA max at $t_A = 25^\circ\text{C}$ $V_{CC} \approx 3.0\text{V}$
 - 100 nA max at $t_A = 25^\circ\text{C}$ $V_{CC} \approx 5.5\text{V}$
 - 1 μA max at $t_A = 60^\circ\text{C}$ $V_{CC} = 5.5\text{V}$
- Full operation for $V_{CC} = 4.5\text{V}$ to 5.5V
- Data Retention Voltage = 5.5V to 2.0V
- Access time equals 200 ns at 5.0V
- Operating temperature range of -40°C to $+85^\circ\text{C}$
- Full static operation
- TTL compatible inputs and outputs
- Available in 28-pin DIP and 28-pin SOIC packages
- Suitable for both battery operated and battery backup applications

PIN ASSIGNMENT



DS2064-200 28-PIN DIP (600 MIL)
 DS2064S-200 28-PIN SOIC (330 MIL)

PIN DESCRIPTION

A0-A12	- Address Inputs
DQ0-DQ7	- Data Input/Output
CE1, CE2	- Chip Enable Inputs
WE	- Write Enable Input
OE	- Output Enable Input
V _{CC}	- 5V Power Supply Input
GND	- Ground
NC	- No Connection

DESCRIPTION

The DS2064 is a 65536-bit low power, fully static random access memory organized as 8192 words by eight bits using CMOS technology. The device operates from a single power supply with a voltage input between 4.5V and 5.5V. The chip enable inputs (CE1 and CE2) are used for device selection and can be used in order to achieve the minimum standby current mode, which fa-

cilitates both battery operate and battery backup applications. The device provides fast access time of 200 ns and is most suitable for low power applications where battery operation or battery backup for nonvolatility is required. The DS2064 is a JEDEC-standard 8K x 8 SRAM and is pin-compatible with ROM and EPROM of similar density.